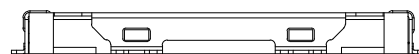
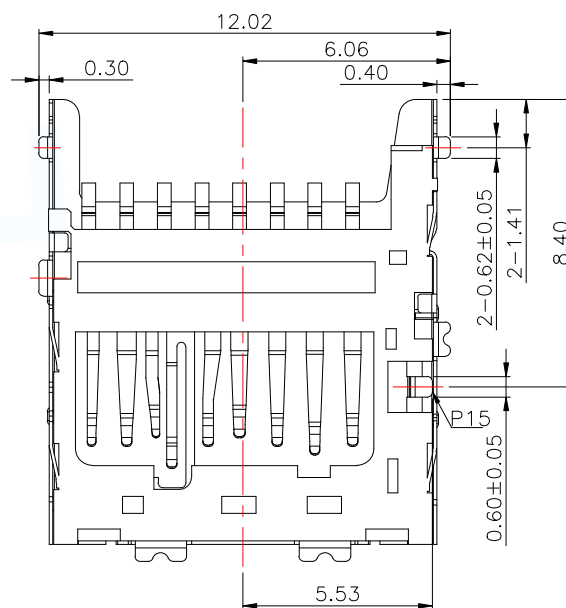
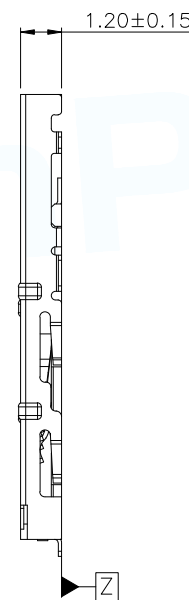
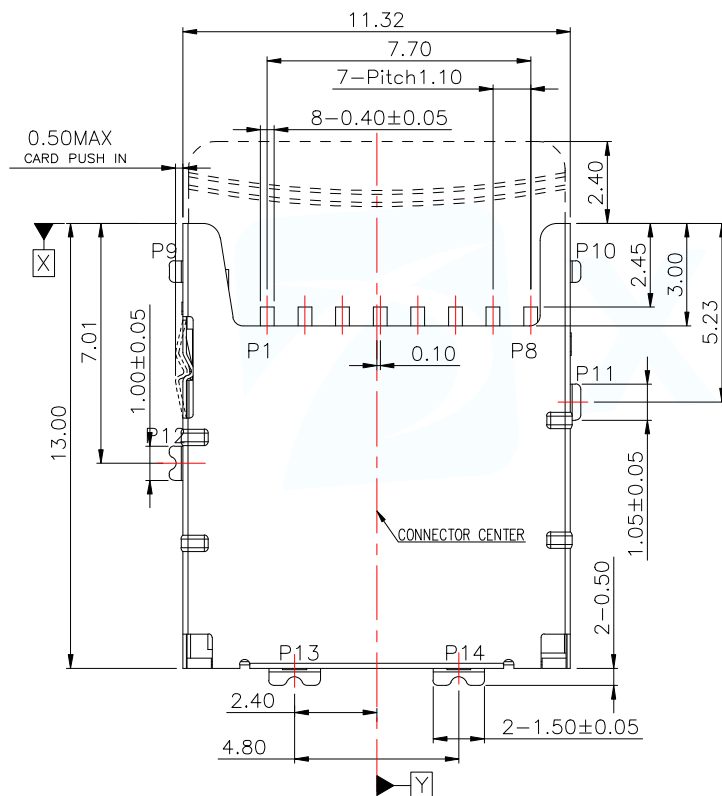
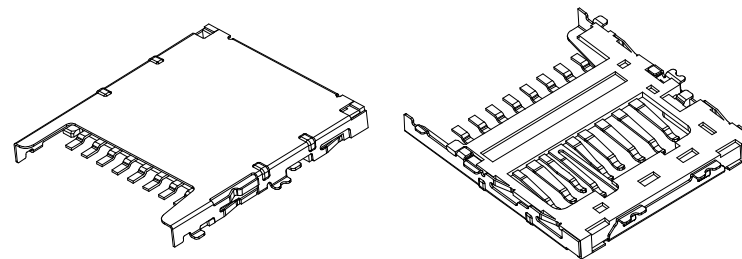
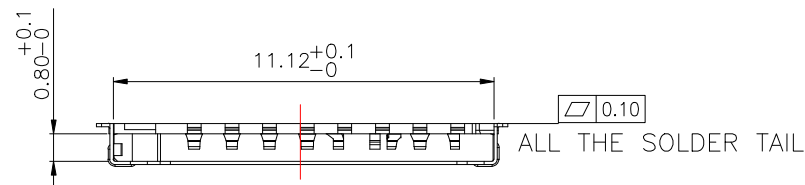
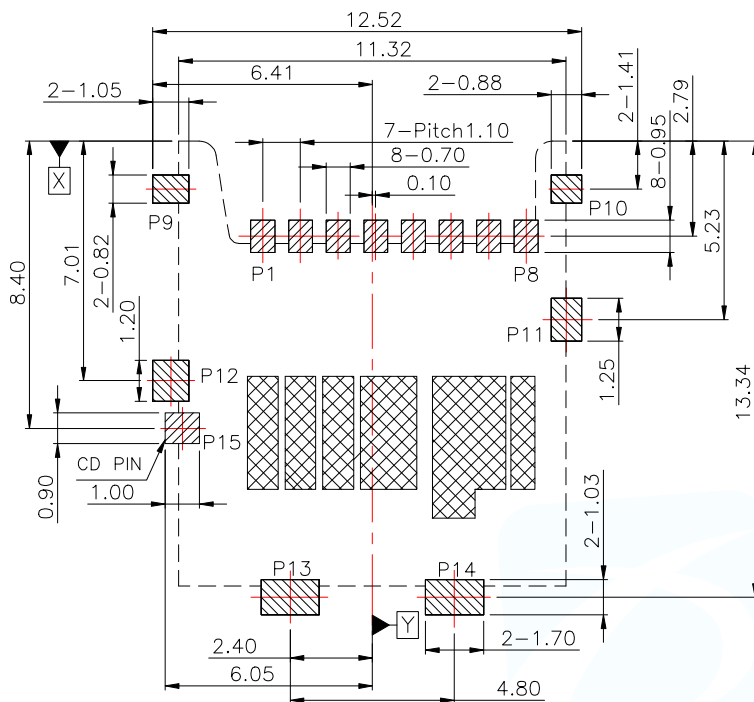


MAPX	MODIFICATION	DATE	DRAW	APPROVE

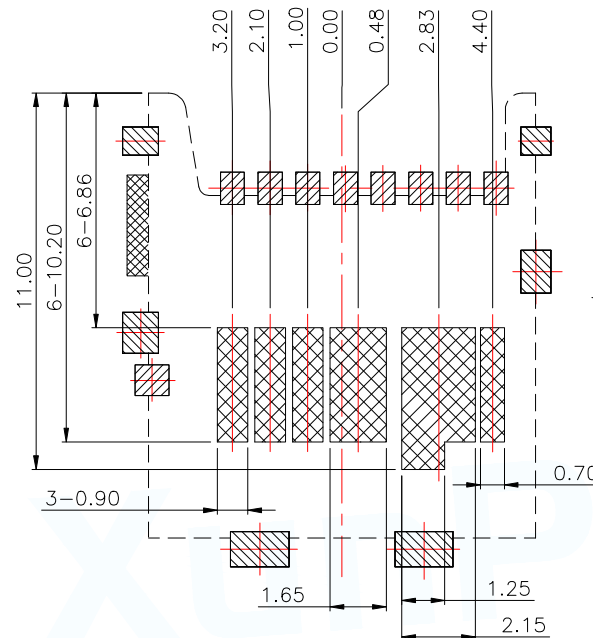


MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: Micro-SD 1.15H connector		
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	TF-129-ARP8	
DECIMALS:	ANGLES:	DWN			
.X:±0.38	X':±2°	CHKD			
.XX:±0.10	X.X':±1°	APVD			
.XXX:±0.05		SCALE1:1	UNIT:MM		
CUSTOMER COPY		SIZE:A4	SHEET:1F1	REV:A	

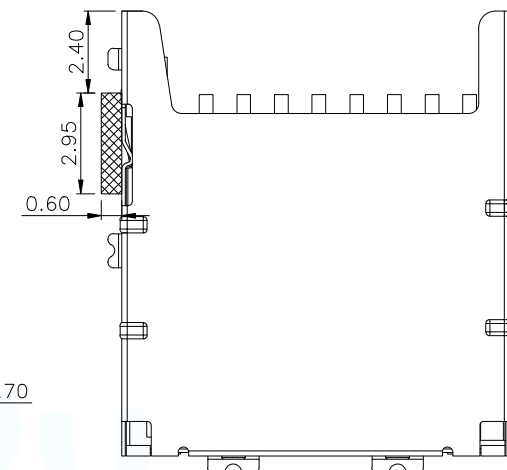




PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)



- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA
(NO Trace&Via&GND)
- GND PATTERN ONLY



No component area

Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	GND
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND
P15	CD

NOTE:

1. Material:
 - 1-1 Housing:High Temperature Thermoplastic,(LCP MG350)Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze(C5210R-SH T=0.12mm)
 - 1-3 Cover: SUS304-H T=0.10mm
- 2.Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Plated 80u"min Sn .
 - Underplating: Ni overall 50U" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 50U" Min.
 - Solder area: Gold 0.8u" Min .
3. Specification:
 - 3-1.Contact Current Rating:0.5Amperes.
 - 3-2.Dielectric Withstanding Voltage:AC500V r.m.s.
 - 3-3.Insulation Resistance:1000 Megohms
 - 3-4.Minimum At DC 500V.
 - 3-5.Contact Resistance:100 mΩ Maximum.
 - 3-6.Mating Cycles:10,000 Cycles.
 - 3-7.Operating Temperature:-25°C~+85°C.

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		SIZE:A4	SHEET:1F1	REV:A